

ABSTRACT

A device for soldering contacts on semiconductor chips. A chip is held on a chip mount by a chuck and is heated from a side facing away from the wafer by means of a radiation source, so that a solder applied to a side facing the wafer is melted. A flushing device, having a plate with a window, a gas channel, and a gas outlet opening for a forming gas, is arranged at the window, is fitted parallel to the wafer. The chip is moved vertically in relation to the wafer, pressed onto the wafer through the window, and soldered on by means of isothermal solidification.